

Intel® Whitley 1U Thermal Module

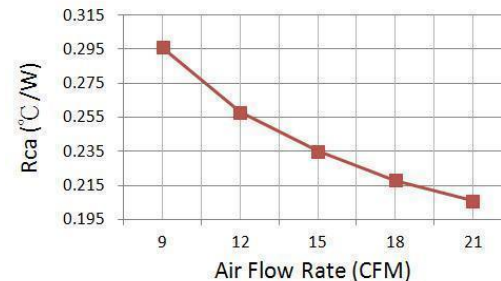


產品名稱 Product Name	Intel® Whitley 1U Thermal Module
產品型號 Product Model	LGA4189-M71
應用市場 Application	Server
晶片平臺 CPU(Chip) Platform	Intel® Whitley LGA 4189 1U
測試環境 Test Condition	Ambient Temp (°C): 25°C Ambient Humidity (RH): 53% Flow (CFM): 30 ~ 50CFM Heatsink Grease: X-23-7762
外形尺寸 (mm) Volumetric	L113 * W79 * H25 (mm)
產品重量(g) Product Weight	240±10g
安裝方式 Mounting Type	Anti-Tilt
工藝類別 Technical Process	Full Al-Extrusion
方案描述 Design Description	Al 6063+CU1100+3PIPE Fin : T0.30mm, P1.50mm

■ Thermal Performance

Item	Air Flow (CFM)	ΔP (mm-Aq)	Tc(°C)	Ta (°C)	ΔT (°C)	Power(w)	Rca(°C/W)
1	20	1.32	75.70	25.10	50.60	230.000	0.2200
	25	1.97	71.00	25.00	46.00	230.000	0.2000
	30	2.56	67.80	25.50	42.30	230.000	0.1839
	35	2.56	65.40	25.60	39.80	230.000	0.1730
	40	1.97	62.80	24.90	37.90	230.000	0.1648
2	20	1.97	61.80	24.80	37.00	165.000	0.2242
	25	2.56	58.00	24.80	33.20	165.000	0.2012
	30	1.97	55.40	24.90	30.50	165.000	0.1848
	35	2.56	54.10	25.20	28.90	165.000	0.1752
	40	2.56	52.30	24.90	27.40	165.000	0.1661

Rca VS Air Flow Rate Chart



ΔP VS Air Flow Rate Chart

